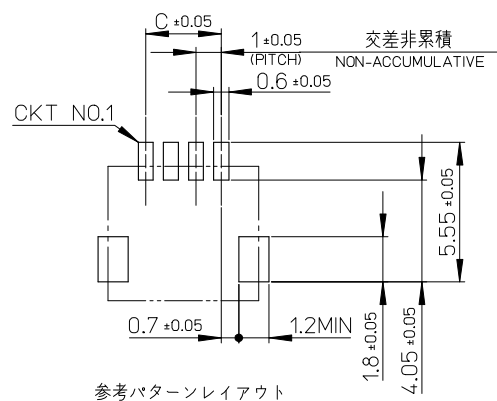
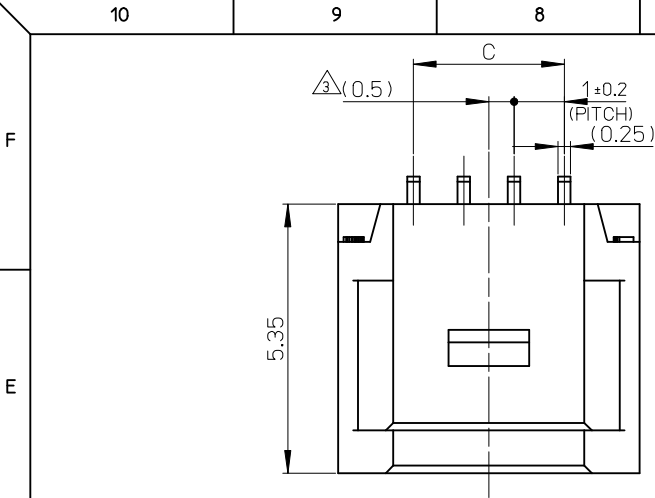
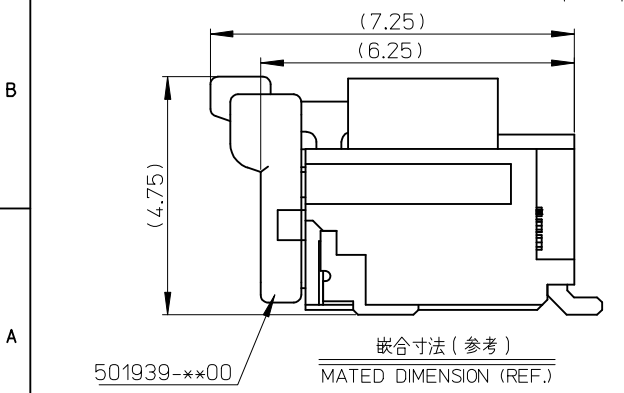
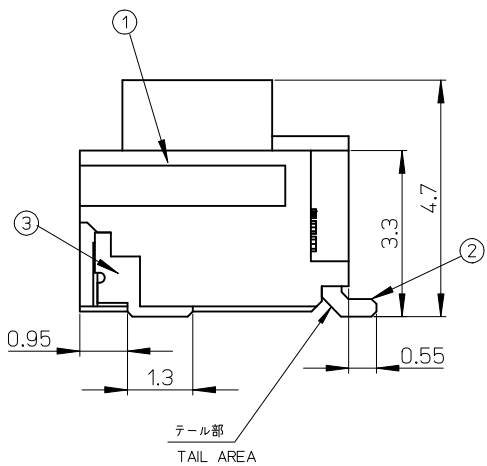
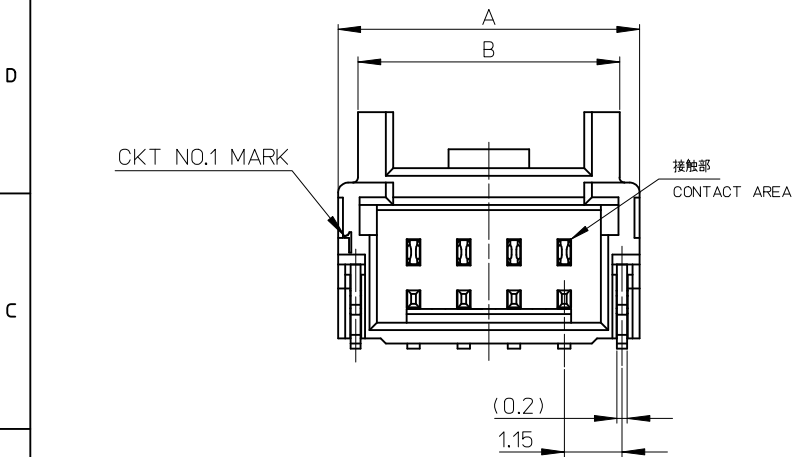




参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF)
SCALE 5:1



番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ (接触部):0.1μm MIN. GOLD PLATING (CONTACT AREA) 金メッキ (テール部):0.05μm MIN. GOLD PLATING (TAIL AREA) ニッケルメッキ (下地):1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ:1.0μmMIN. TIN ニッケルメッキ (下地):1.0μmMIN. NICKEL(UNDER PLATING)

- NOTES.
- 嵌合相手: 501939-****
MATE WITH: 501939-****
 - ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT. SIZE=EVEN
4.ELV AND RoHS COMPLIANT.

4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

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REVISED EC NO: J2016-1063 DRWNR: TANAKA02 CHKD: SAKIYAMA APPR: TKANEKO	DESCRIPTION REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK					
		0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25						
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex					
		1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25						
		10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SD-501953-003					
		30 OVER		±0.3	NUKITA	2015/01/16						
		ANGULAR ±3 °			MATERIAL NO.		DOCUMENT NO.				SHEET NO.	
					SEE SHEET 2						1 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

	紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
					5
					4
					3
	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***9					
青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
				501953-0505	5
				501953-0405	4
				501953-0305	3
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***6					

REVISED		EC NO.: J2016-1063		2016/04/07 2016/04/08 2016/04/28		DRWNR: TANAKA02 CHKD: SAKI YAMA APPR: IKANEKO		DESCRIPTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
										0.25 UNDER UNDER ± 0.03		DRAWN BY DATE		TITLE					
										0.25 OVER 0.5 UNDER ± 0.05		KCHIKANO 2014/12/25							
										0.5 OVER 1.0 UNDER ± 0.1		CHECKED BY DATE							
										1.0 OVER 10 UNDER ± 0.2		KASAKAWA 2014/12/25							
										10 OVER 30 UNDER ± 0.25		APPROVED BY DATE							
										30 OVER ± 0.3		NUKITA 2015/01/16							
										ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.	
												SEE CHART		SD-501953-003				2 OF 2	
A										DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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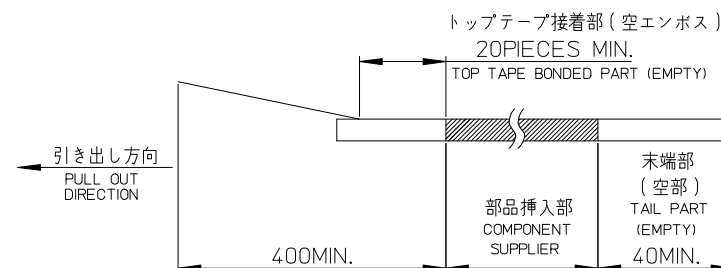
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NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS,PLEASE SEE THE DRAWING OF CONNECTOR ITSELF(NOT PACKAGED).
- 梱包数量：1300個/リール
NUMBER OF CONNECTORS : 1300PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



4. 材料

MATERIAL

キャリアテープ：ポリスチレン

CARRIER TAPE : POLYSTYRENE

トップテープ：PET、その他

TOP TAPE:PET,OTHER

リール：ポリスチレン<リサイクル材を含む>

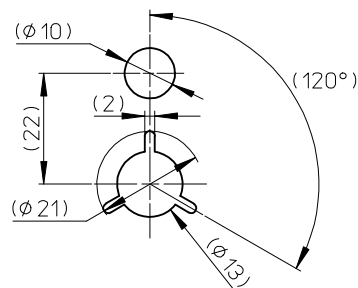
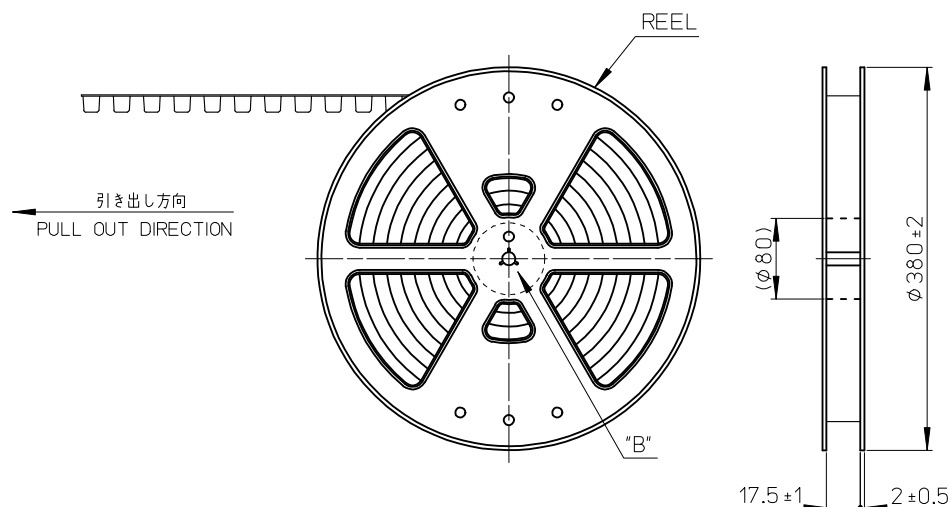
REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED >

5.ELV AND RoHS COMPLIANT.

6. ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-**07除く)

THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501953-**07)

7. 開梱後の保管条件に注意のこ。 (ハイバリア品対象:PS-501940-001参照)

REFER TO PS-501940-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

DETAIL "B"

REVISED EC NO: J2016-1063 DRAWN:RTANAKAO2 CHKD:SAK IYAWA APPR:TKANEKO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER UNDER ±0.03	DRAWN BY DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG							
		0.25 OVER 0.5 UNDER ±0.05	KCHIKANO 2014/12/25								
		0.5 OVER 1.0 UNDER ±0.1	CHECKED BY DATE	DOCUMENT NO. molex							
		1.0 OVER 10 UNDER ±0.2	KASAKAWA 2014/12/25								
		10 OVER 30 UNDER ±0.25	APPROVED BY DATE	SHEET NO. 1 OF 3							
		30 OVER ±0.3	NUKITA 2015/01/16								
		ANGULAR ±3 °			MATERIAL NO.		SEE SHEET3 SD-501953-004				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3						

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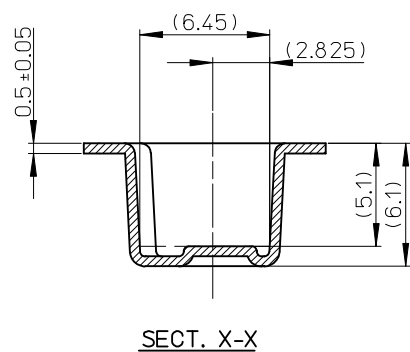
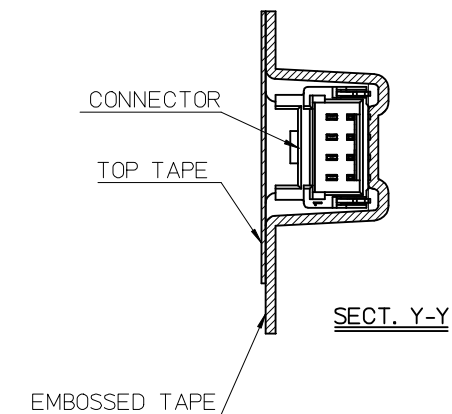
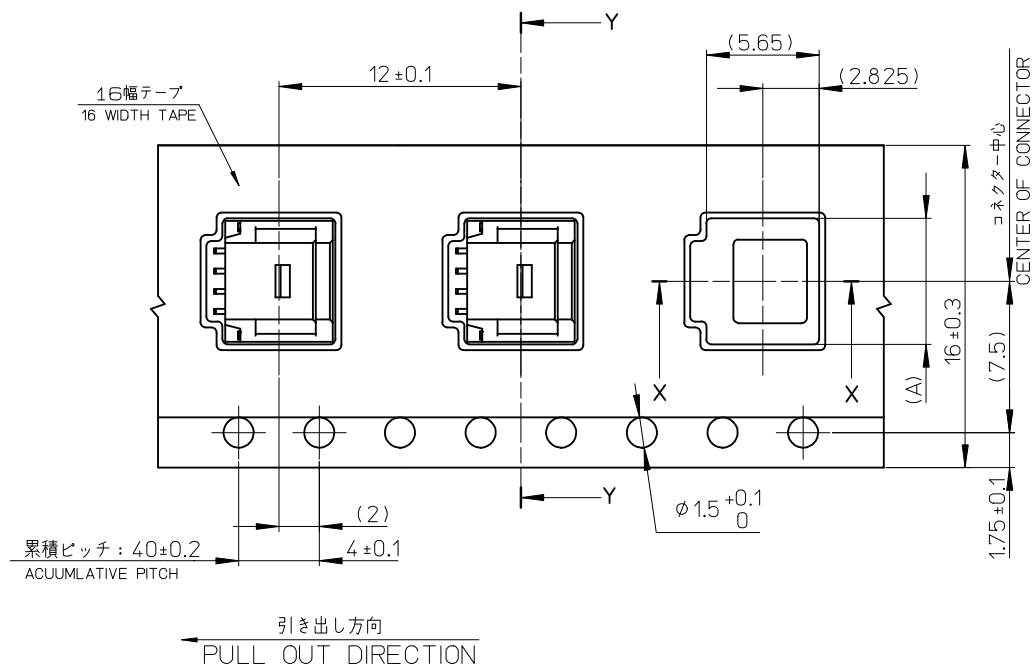
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7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-***6

REVISED EC NO: J2016-1063 DRWNR:ANAKA02 CHKD:SAK IYAMA APPR:TKANEKO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG	molex	SHEET NO. 2 OF 3	
		0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25				
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	DOCUMENT NO. SD-501953-004	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25				
		10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SEE SHEET 3			
		30 OVER		±0.3	NUKITA	2015/01/16				
		ANGULAR ±3 °			MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3					
		A	REV							

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紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
				5
				4
				3
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 501953-***9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
				501953-0505	5
				501953-0405	4
				501953-0305	3
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 501953-***6

REVISED EC NO: J2016-1063 DRAWN: TANAKA02 CHKD: SAKIYAMA APPR: KANEKO A	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		0.25	UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG molex				
		0.25	OVER	0.5	UNDER	± 0.05	KCHIKANO					2014/12/25
		0.5	OVER	1.0	UNDER	± 0.1	CHECKED BY					DATE
		1.0	OVER	10	UNDER	± 0.2	KASAKAWA	2014/12/25	DOCUMENT NO. SD-501953-004 SHEET NO. 3 OF 3			
		10	OVER	30	UNDER	± 0.25	APPROVED BY	DATE				
		30	OVER		± 0.3	NUKITA	2015/01/16					
	ANGULAR			±3 °	MATERIAL NO.							
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	SEE CHART THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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